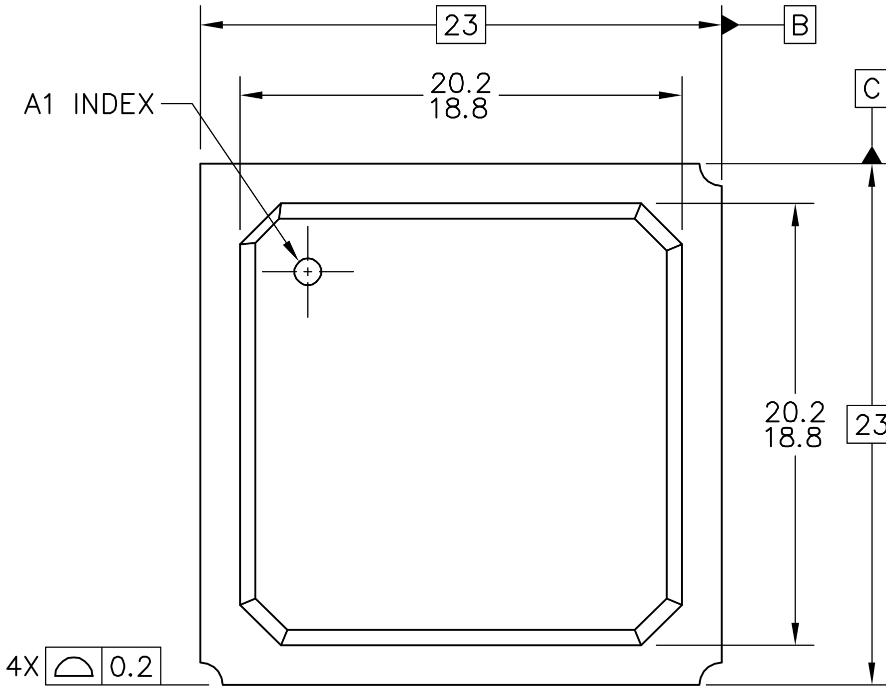

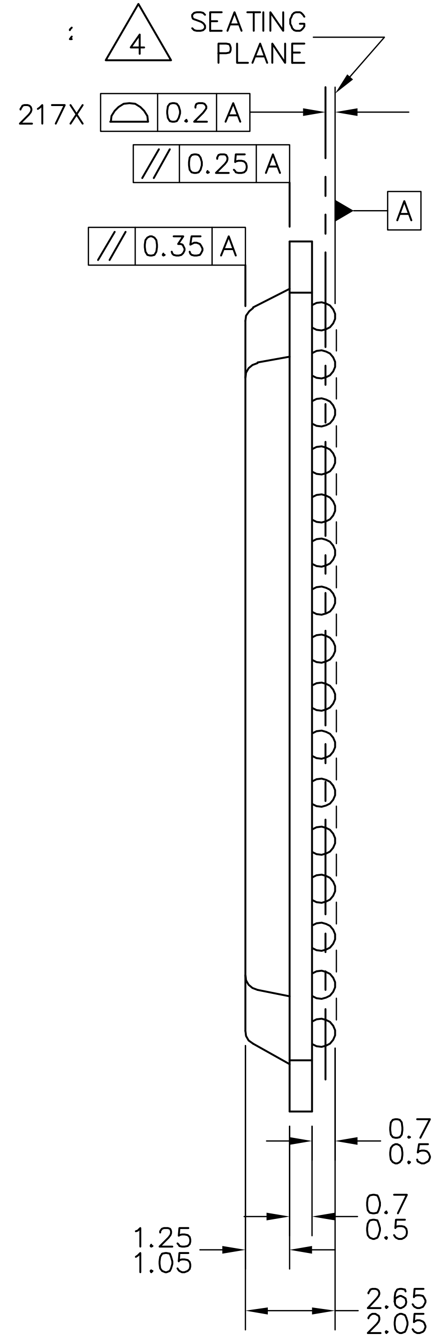

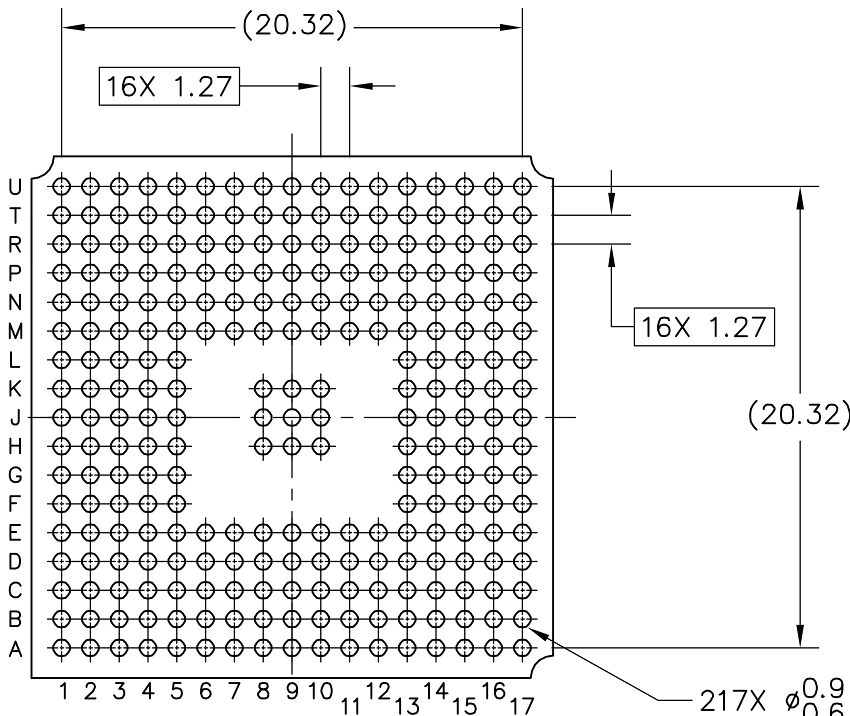

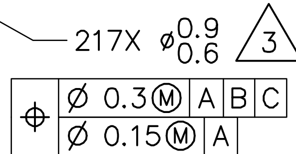

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TITLE: 217 I/O PBGA 23 X 23, 1.27 MM PITCH	DOCUMENT NO: 98ASS23770W	REV: B
	STANDARD: JEDEC MO-151 BAL-2	
	SOT710-2	29 FEB 2016

NOTES:

1. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M−1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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